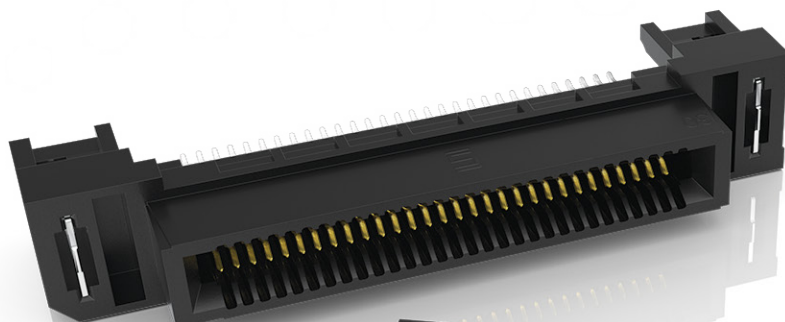


GENERATE[®]

HIGH-SPEED EDGE CARD SYSTEMS

0.60 mm, 0.80 mm and 1.00 mm PITCH

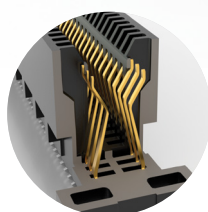
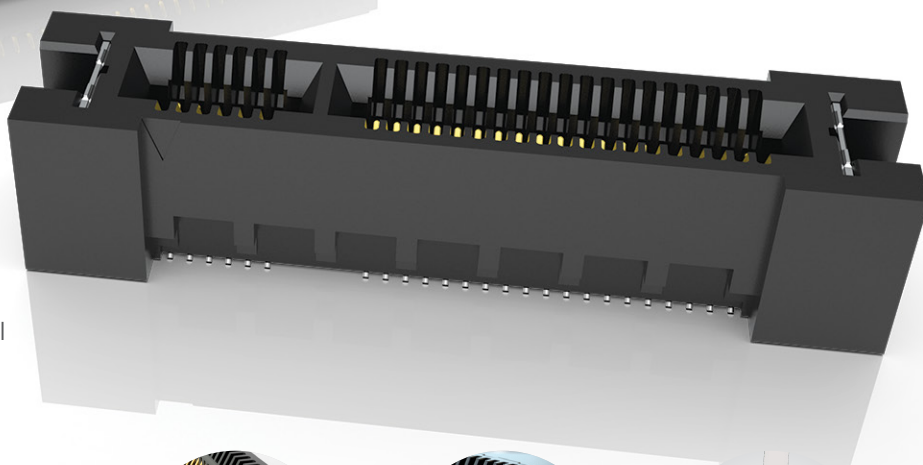


**EDGE
RATE[®]**
CONTACT

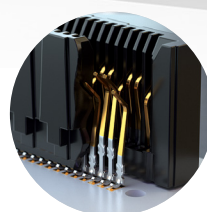
FEATURES & BENEFITS

- Maximum Design Flexibility
- Up to 64 Gbps PAM4 performance
- PCI Express[®] 3.0, 4.0, 5.0 and 6.0
- Edge Rate[®] contacts optimized for signal integrity performance and high-cycle life
- Up to 200 positions available
- Vertical, right-angle, edge mount, pass-through orientations
- Power/signal combo, press-fit tails, rugged weld tabs, locks and latches
- Mating cable assemblies available

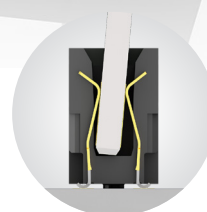
The PCI Express[®] design marks are registered trademarks and/or service marks of PCI-SIG.



Rugged tucked
beam technology
(HTEC8)



Differential pair for
increased speed
(HSEC8-DP)



Custom designs allow
for misalignment in
the X-Y axes (HSEC1)

KEY SPECIFICATIONS

SERIES	PITCH	TOTAL POSITIONS	INSULATOR MATERIAL	CONTACT MATERIAL	OPERATING TEMP RANGE	CURRENT RATING	VOLTAGE RATING	LEAD-FREE SOLDERABLE
HSEC6	0.60 mm	56-168	Black LCP	Copper Alloy	-55 °C to +125 °C	1.9 A (2 pins)	240 VAC/339 VDC	Yes
HTEC8	0.80 mm	20-200	Black LCP	Copper Alloy	-55 °C to +125 °C	3.0 A (2 pins)	215 VAC/304 VDC	Yes
HSEC8-DV	0.80 mm	18-200	Black LCP	BeCu	-55 °C to +125 °C	2.8 A (2 pins)	240 VAC/339 VDC	Yes
HSEC8-RA	0.80 mm	18-120	Black LCP	BeCu	-55 °C to +125 °C	2.6 A (2 pins)	175 VAC/247 VDC	Yes
HSEC8-EM	0.80 mm	20-120	Black LCP	BeCu	-55 °C to +125 °C	2.8 A (2 pins)	240 VAC/339 VDC	Yes
HSEC8-PE	0.80 mm	20-40	Black LCP	BeCu	-55 °C to +125 °C	2.8 A (2 pins)	240 VAC/339 VDC	Yes
HSEC8-PV	0.80 mm	40-80	Black LCP	BeCu	-55 °C to +125 °C	3.2 A (2 pins)	215 VAC/304 VDC	Yes
HSEC8-DP	0.80 mm	16-112	Black LCP	BeCu	-55 °C to +125 °C	2.7 A (2 pins)	235 VAC/332 VDC	Yes
HSEC1	1.00 mm	20-140	Black LCP	Phosphor Bronze	-55 °C to +125 °C	2.2 A (2 pins)	215 VAC/304 VDC	Yes

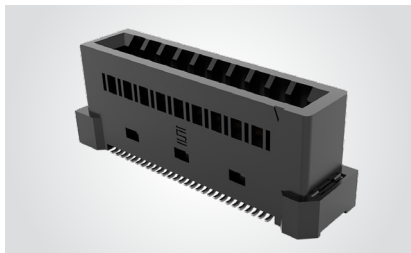
(0.60 mm) .024" PITCH • VERTICAL EDGE CARD SOCKET

HSEC6	POSITIONS PER ROW	CARD THICKNESS	PLATING OPTION	DV	SHIELD OPTION	WT	"X"R
	-028, -042, -070, -084	-01 = (1.60 mm) .062" thick card	-S = 30 μ" (0.76 μm) Gold on contact area, Matte Tin on tail		Leave blank for no shield -S = Shield (not available with -084 positions)	Required for everything but shielded -028 positions -WT = Weld tab	-TR = Tape & Reel -FR = Full Reel Tape & Reel (must order max. quantity per reel; contact Samtec for quantity breaks)

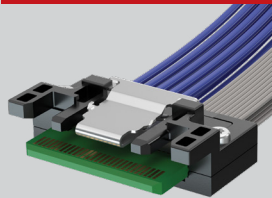
HSEC6

Card Mates:
(1.60 mm)
.062" card

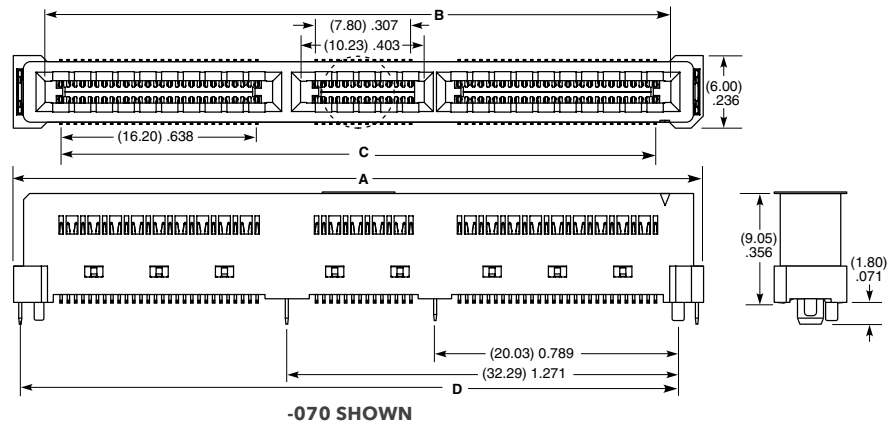
Cable Mates:
GC6



ALSO AVAILABLE



0.60 mm Pitch Mating
High-Speed Cable Assembly.
See GC6 Series.



STANDARDS

SFF-TA-1002

Visit www.samtec.com/standards
for more information.

HIGH-SPEED PAIRS	SFF-TA-1002	POSITIONS PER ROW	A	B	C	D
x4, 8 DP's	1C	-028	(23.88) .940	(18.62) .733	(16.20) .638	(21.18) .834
x8, 16 DP's	2C	-042	(35.60) 1.402	(30.61) 1.205	(28.01) 1.103	(32.90) 1.295
x16, 32 DP's	4C	-070	(57.02) 2.245	(51.72) 2.036	(49.12) 1.934	(54.32) 2.139
	4C+	-084	(69.17) 2.723	(63.92) 2.516	(61.32) 2.414	(66.52) 2.619

Note:
Polyimide film pick & place
pad is standard.

Some sizes, styles and
options are non-standard,
non-returnable

View complete specifications at: samtec.com?HSEC6-DV

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

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[HSEC6-042-01-S-DV-S-TR](#)